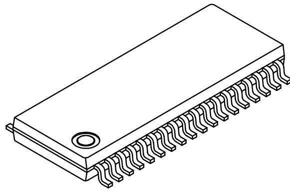
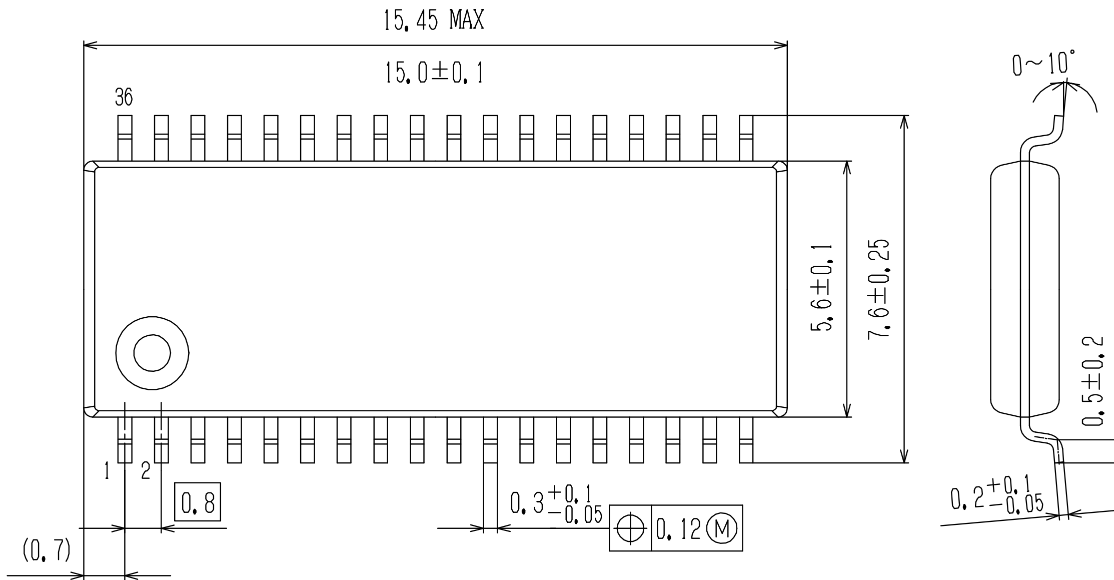
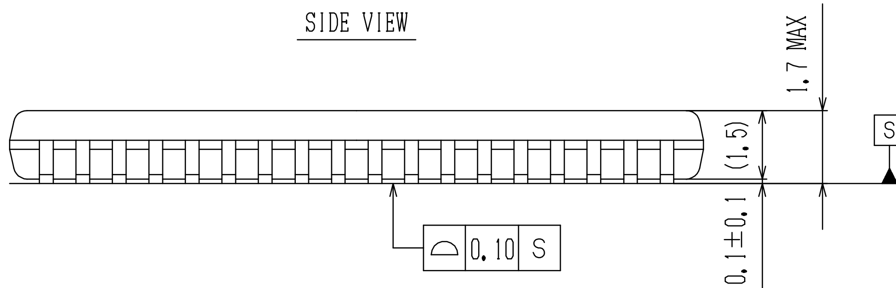
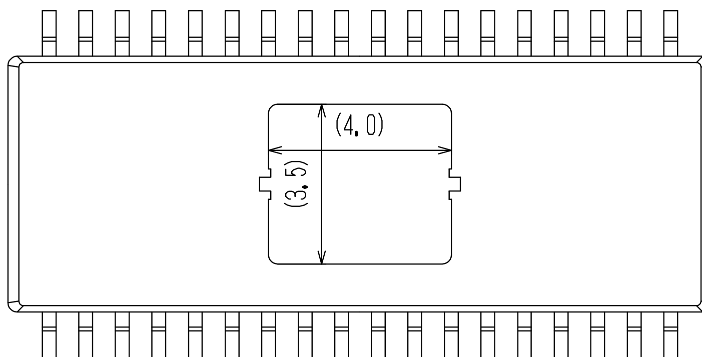


SSOP36J (275mil) Exposed Pad
CASE 940AH
ISSUE A

DATE 25 NOV 2013







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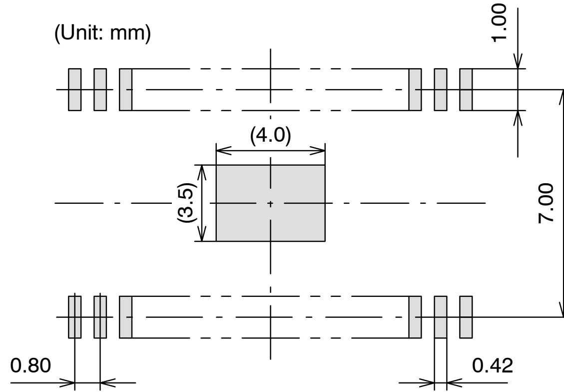
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SSOP36J (275MIL) EXPOSED PAD	PAGE 1 OF 3

SOLDERING FOOTPRINT*

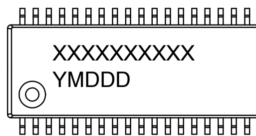


NOTES:

1. The measurements are for reference only, and unable to guarantee.
2. Please take appropriate action to design the actual Exposed Die Pad and Fin portion.
3. After setting, verification on the product must be done.
   (Although there are no recommended design for Exposed Die Pad and Fin portion Metal mask and shape for Through−Hole pitch (Pitch & Via etc), checking the soldered joint condition and reliability verification of soldered joint will be needed. Void ▪ gradient ▪ insufficient thickness of soldered joint or bond degradation could lead IC destruction because thermal conduction to substrate becomes poor.)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	SSOP36J (275MIL) EXPOSED PAD	PAGE 2 OF 3

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM SANYO ENACT# S−420 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	30 JAN 2012
A	ADDED MARKING AND SOLDER FOOTPRINT INFORMATION. REQ. BY D. TRUHITTE.	25 NOV 2013

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